

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Nishant Sinha

Serial No.: 10/668,914

Filed: September 23, 2003

For: PROCESS AND INTEGRATION
SCHEME FOR FABRICATING
CONDUCTIVE COMPONENTS,
THROUGH-VIAS AND
SEMICONDUCTOR COMPONENTS
INCLUDING CONDUCTIVE THROUGH-
WAFER VIAS

Confirmation No.: 2525

Examiner: W. Lindsay Jr.

Group Art Unit: 2812

Attorney Docket No.: 2269-5859US
(02-0390.00/US)

Notice of Allowance Mailed:

March 22, 2007

**VIA ELECTRONIC FILING
JUNE 20, 2007**

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the specification begin on page 3 of this paper;

Amendments to the claims are set forth in the listing of the claims that begins on page 5 of this paper; and

Remarks start at page 8 of this paper.